

PCN Number:	20231013001.1			PCN Date:	October 16, 2023				
Title:	Qualification of TI Chengdu as an alternate Assembly site for select devices								
Customer Contact:	Change Management team		Dept:	Quality Services					
Proposed 1st Ship Date:	Jan 14, 2024		Sample Requests accepted until:	Nov 16, 2023*					
*Sample requests received after Nov 16, 2023 will not be supported.									
Change Type:									
☒	Assembly Site	☐	Design	☐	Wafer Bump Material				
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process				
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site				
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials				
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process				
PCN Details									
Description of Change:									
Texas Instruments Incorporated is announcing the qualification of TI Chengdu as an additional Assembly site for the devices listed below. There are no construction differences between the 2 sites.									
Reason for Change:									
Supply continuity									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									
Impact on Environmental Ratings									
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.									
RoHS		REACH		Green Status					
☒ No Change		☒ No Change		☒ No Change					
				IEC 62474					
				☒ No Change					
Changes to product identification resulting from this PCN:									
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City						
JCAP	JCP	CHN	Jiangyin						
TI Chengdu	CDA	CHN	Chengdu						
Sample product shipping label (not actual product label)									
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: <table border="1"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: 39 LBL: 5A (L)T0:1750  (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS						MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL 2 /260C/1 YEAR	SEAL DT								
MSL 1 /235C/UNLIM	03/29/04								

Product Affected:			
SN61280HYFFR	TPS62802YKAR	TPS62807YKAR	TPS6283612YKAR
TPS62801YKAR			

Qualification Report

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN2001088YBGR	QBS Reference: TMP117AIYBGR	QBS Reference: TMP117MAIYBGR	QBS Reference: TMP117NAIYBGR	QBS Reference: TMP117AIYBGR	QBS Reference: TMP117AIDVR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	3/231/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	-	1/1000/0	-
ESD	E2	ESD CDM	-	1000 Volts	3/9/0	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	3/9/0	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	3/18/0	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	3/90/0	-	-	-	-	-

QBS: Qual By Similarity

Qual Device SN2001088YBGR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS562231DRLR
ED	Electrical Characterization, side by side	(per datasheet)	Pass
FLAM	Flammability (UL-1694)	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0
LFA	Lead Finish Adhesion	Leads	3/45/0
LI	Lead Fatigue	Leads	3/54/0
LI	Lead Pull	Leads	3/72/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
SA	Salt Atmosphere	24 Hrs	3/66/0
SD	Solderability	Pb Free	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0
VM	Visual / Mechanical	-	3/984/0

- Qual Device TPS562231DRLR is qualified at LEVEL1-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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